



## Material Content Data Sheet



<b>Sales Product Name</b>		BTS3160D		<b>Issued</b>		31. July 2018		
<b>MA#</b>		MA001589168						
<b>Package</b>		PG-TO252-5-13		<b>Weight*</b>		430.15 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip_1	inorganic material	silicon	7440-21-3	4.029	0.94	0.94	9365	9365
chip_2	inorganic material	silicon	7440-21-3	0.969	0.23	0.23	2254	2254
leadframe	inorganic material	phosphorus	7723-14-0	0.088	0.02		204	
	non noble metal	iron	7439-89-6	0.293	0.07		681	
	non noble metal	copper	7440-50-8	292.340	67.95	68.04	679619	680504
	non noble metal	aluminium	7429-90-5	1.837	0.43	0.43	4272	4272
wire	non noble metal	aluminium	7429-90-5	1.837	0.43	0.43	4272	4272
encapsulation	organic material	carbon black	1333-86-4	1.217	0.28		2829	
	plastics	epoxy resin	-	21.294	4.95		49503	
	inorganic material	silicondioxide	60676-86-0	99.169	23.05	28.28	230545	282877
leadfinish	non noble metal	tin	7440-31-5	5.440	1.26	1.26	12647	12647
plating	inorganic material	phosphorus	7723-14-0	0.000	0.00		1	
	non noble metal	nickel	7440-02-0	0.089	0.02	0.02	206	207
solder	non noble metal	tin	7440-31-5	0.065	0.02		150	
	noble metal	silver	7440-22-4	0.081	0.02		188	
	non noble metal	lead	7439-92-1	3.085	0.72	0.76	7172	7510
glue	plastics	Polyimide	26023-21-2	0.157	0.04	0.04	364	364
*deviation	< 10%		Sum in total:			100.00		1000000

### Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com